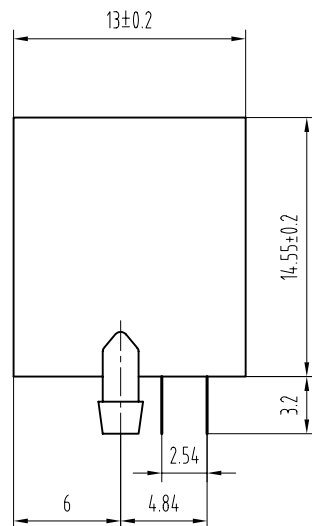
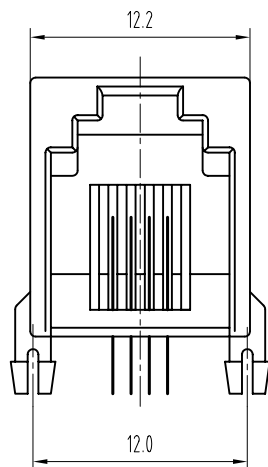


PC Board Layout
Front Side Shown

NOTES:

MATERIAL :

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
2.CONTACT MATERIAL :PHOSPHOR BRONZE $\phi 0.46\text{mm}$.
3.PLATING :GOLD PLATING OVER NICKEL.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
2.CURRENT RATING :1.5 AMP.
3.CONTACT RESISTANCE :30 MILLIOHMS MAX.
4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40℃~+85℃
2. OPERATION : 0℃ TO 70℃



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: RJ11 90 ° DIP 6P4C
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW48-RJ11-130B
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-2111031521
			SHEET NO. 1 OF 1